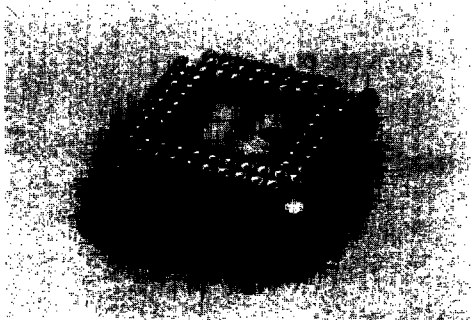


Largest Selection of Footprints



Custom Configurations



Hybrid PGA Sockets



True Surface Mount PGA Sockets
Patent Pending

Pin Grid Array Sockets

McKenzie Technology is the source for Pin Grid Array Sockets. We offer the largest selection of footprints and contact options in the industry.

State of the art, on-site molding and automated assembly mean unbeatable quality and delivery at a very competitive price.

With a reputation built on engineered innovation, our PGA Socket family includes many leading edge products designed to deliver solutions for your most difficult requirements.

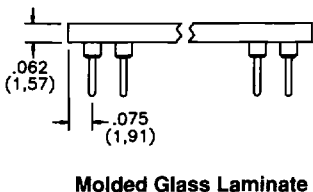
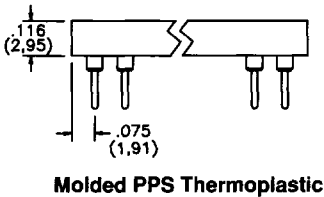
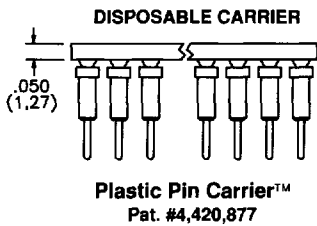
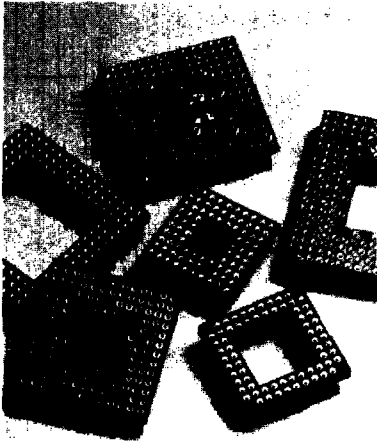
Among these are:

- Ultra Low Insertion Force (ULIF) screw machine contacts with a third of the insertion/extraction forces found in industry standard PGA Sockets (recommended for pin counts greater than 150).
- Extremely low profile (.016" (0,40) above board height) contacts on our patented plastic disposable carrier system for applications short on head room or needing the lowest lead length possible to minimize the inductance and capacitance impact on your high speed circuit.
- True surface mount PGA Sockets designed from the ground up to meet the criteria for surface mounted devices: 100% inspectability of all solder joints, $\pm .002$ " coplanarity, a center tab for pick and place, and surface mount compatible materials.
- Customer specific Circuit Correction and Hybrid Sockets designed to correct bugs in ASIC's and errors in board layouts.

If you do not find the PGA Socket you are looking for in this section please complete the worksheet found on page F10 of this catalog and fax it to us.

Standard to custom, no one does it better!

F



Sockets from the Industry's Source!

- Largest selection of molded PGA footprints
- Widest variety of contact styles — over 140 contact options listed in Section A
- Insulator materials that meet your toughest Hi-temp application needs
- Contact options ensure the lowest possible insertion and extraction forces
- Custom patterns and high pin count PGA's are our specialty.

Plastic Pin Carrier™ Option

- Rigid disposable carrier
- Ultra low profile applications as low as .016" (0,40) max. above the surface of your board
- Self masks against solder, flux, and solvent contamination
- Ideal for high speed systems to reduce propagation delays by shortening interconnect paths between devices.

Standard Materials

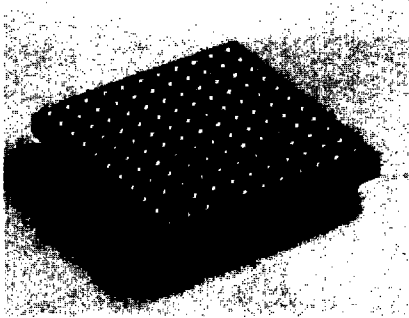
Glass Reinforced Polyester Thermoplastic — UL 94V-0
Continuous use Temperature: -55°C to 140°C, Molded Body



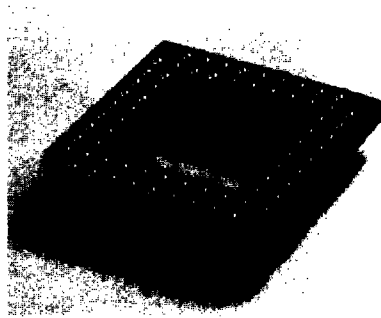
Hi-temp Insulator Materials

- F FR4** Glass Reinforced Epoxy Laminate, UL 94V-0, ≤140°C
- R PPS** Glass Reinforced Polyphenylene Sulfide, UL 94V-0, ≤220°C
- H Hi-3003** Glass Reinforced Polyimide Laminate, UL 94V-0, ≤250°C

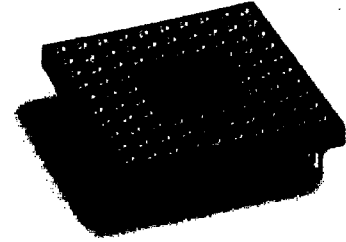
INSULATOR CENTER OPTIONS



Full matrix of holes-option "M"

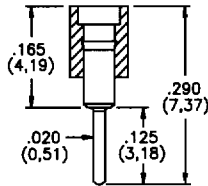


Square center hole-option "H"



Solid center-option "S"

OUR MOST POPULAR CONTACTS



Specify	Contact/Shell
003B*	30μ" Gold/200μ" Tin
004B*	30μ" Gold/10μ" Gold
012B*	10μ" Gold/200μ" Tin
015B*	200μ" Tin/200μ" Tin
008B [§]	10μ" Gold/200μ" Tin
009B [§]	30μ" Gold/200μ" Tin

* Very low insertion force
 § Ultra low insertion force

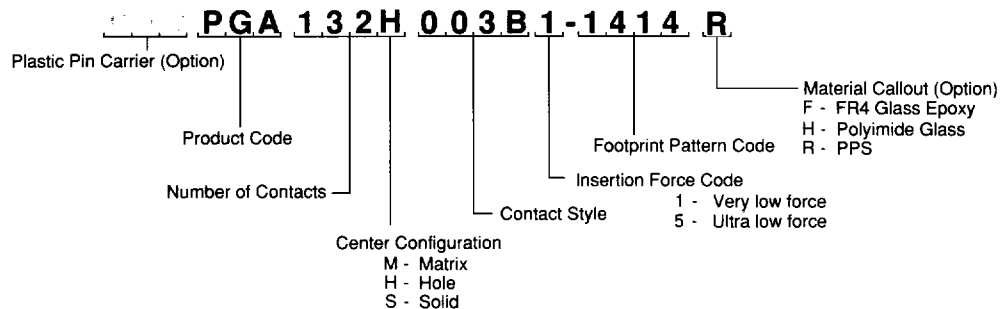
Follow These Steps to Order:

1. Select pattern and socket body center style from this section
2. Choose contact style from table at left or, from Section A
3. Determine insulator material best suited to your application or use Plastic Pin Carrier™.
4. Please call for application assistance or samples

Insertion Force Note: McKenzie Technology strongly recommends using a Ultra Low Insertion Force (ULIF) style contact where the pin count exceeds 150 pins.



How to Order a PGA Socket



MOLDED SOCKETS

